

## Electronic Patent Application Fee Transmittal

Application Number:	10809182			
Filing Date:	25-Mar-2004			
Title of Invention:	Resin composition for encapsulating semiconductor chip and semiconductor device therewith			
First Named Inventor/Applicant Name:	Kuniharu Umeno			
Filer:	Robert G. Weilacher/Susan Revell			
Attorney Docket Number:	033036.076			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>120</b>